

IPS031/IPS031S

FULLY PROTECTED POWER MOSFET SWITCH

Features

- Over temperature shutdown
- Over current shutdown
- Active clamp
- Low current & logic level input
- E.S.D protection

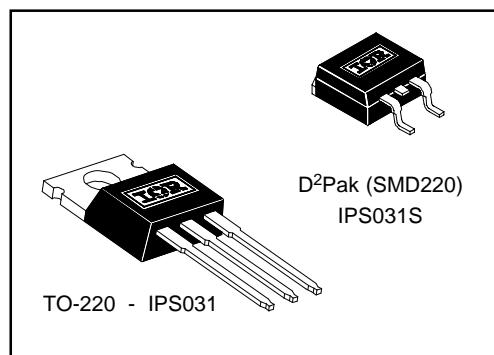
Description

The IPS031/IPS031S are fully protected three terminal SMART POWER MOSFETs that feature over-current, over-temperature, ESD protection and drain to source active clamp. These devices combine a HEXFET® POWER MOSFET and a gate driver. They offer full protection and high reliability required in harsh environments. The driver allows short switching times and provides efficient protection by turning OFF the power MOSFET when the temperature exceeds 165°C or when the drain current reaches 12A. The device restarts once the input is cycled. The avalanche capability is significantly enhanced by the active clamp and covers most inductive load demagnetizations.

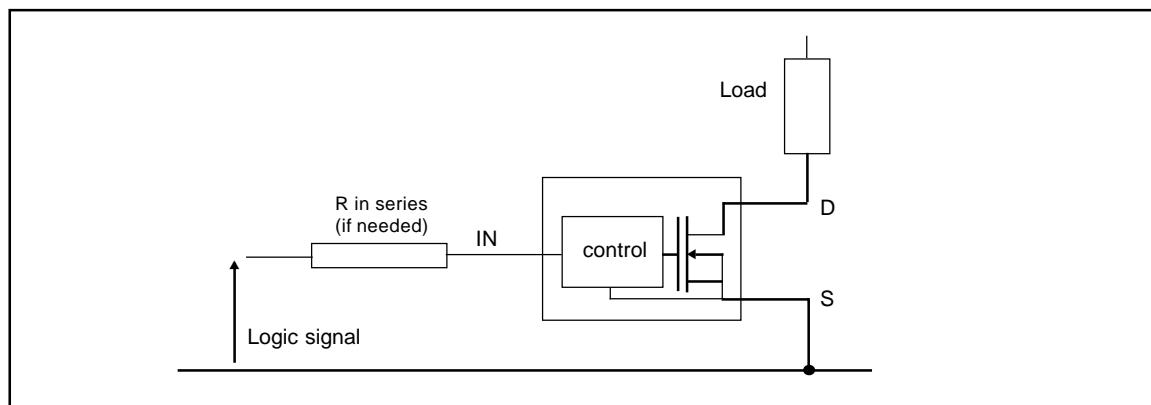
Product Summary

$R_{ds(on)}$	60mΩ (max)
V_{clamp}	50V
I_{shutdown}	12A
$T_{\text{on}}/T_{\text{off}}$	1.5μs

Packages



Typical Connection



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Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are referenced to SOURCE lead. (TAmbient = 25°C unless otherwise specified). PCB mounting uses the standard footprint with 70 µm copper thickness.

Symbol	Parameter	Min.	Max.	Units	Test Conditions
V _{ds}	Maximum drain to source voltage	—	47	V	
V _{in}	Maximum input voltage	-0.3	7		
I _{in, max}	Maximum IN current	-10	+10	mA	
I _{sd cont.}	Diode max. continuous current (1) r _{th} =62°C/W IPS031	—	2.8	A	
					TO220 free air
					TO220 with R _{th} =5°C/W
	r _{th} =80°C/W IPS031S	—	2.2		SMD220 Std. footprint
I _{sd pulsed}	Diode max. pulsed current (1)	—	18		
P _d	Maximum power dissipation ⁽¹⁾ (r _{th} =62°C/W) IPS031	—	2	W	
ESD1	Electrostatic discharge voltage (Human Body)	—	4	kV	C=100pF, R=1500Ω,
	ESD2	Electrostatic discharge voltage (Machine Model)	—		C=200pF, R=0Ω, L=10µH
T _j max.	Max. storage & operating junction temp.	-40	+150	°C	
T _{lead}	Lead temperature (soldering, 10 seconds)	—	300		

Thermal Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R _{th} 1	Thermal resistance free air	—	60	—	°C/W	TO-220
R _{th} 2	Thermal resistance junction to case	—	3	—		
R _{th} 1	Thermal resistance with standard footprint	—	80	—		D ² PAK (SMD220)
R _{th} 2	Thermal resistance with 1" square footprint	—	60	—		
R _{th} 3	Thermal resistance junction to case	—	3	—		

Recommended Operating Conditions

These values are given for a quick design. For operation outside these conditions, please consult the application notes.

Symbol	Parameter	Min.	Max.	Units
V _{ds} (max)	Continuous drain to source voltage	—	35	V
V _{IH}	High level input voltage	4	6	
V _{IL}	Low level input voltage	0	0.5	A
I _{ds} T _{amb} =85°C	Continuous drain current (TAmbient = 85°C, IN = 5V, r _{th} = 60°C/W, T _j = 125°C) IPS031	—	3.1	
	(TAmbient = 85°C, IN = 5V, r _{th} = 80°C/W, T _j = 125°C) IPS031S	—	2.8	
R _{in}	Recommended resistor in series with IN pin	0.2	5	kΩ
T _{r-in(max)}	Max recommended rise time for IN signal (see fig. 2)	—	1	µS
F _r -I _{sc} ⁽²⁾	Max. frequency in short circuit condition (V _{cc} = 14V)	0	1	kHz

(1) Limited by junction temperature (pulsed current limited also by internal wiring)

(2) Operations at higher switching frequencies is possible. See Appl. Notes.

Static Electrical Characteristics

($T_j = 25^\circ\text{C}$ unless otherwise specified.)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
Rds(on)	ON state resistance $T_j = 25^\circ\text{C}$	20	45	60	$\text{m}\Omega$	$V_{in} = 5\text{V}$, $I_{ds} = 1\text{A}$
Rds(on)	ON state resistance $T_j = 150^\circ\text{C}$	—	75	100		
Idss @ $T_j=25^\circ\text{C}$	Drain to source leakage current	0	0.5	25	μA	$V_{cc} = 14\text{V}$, $T_j = 25^\circ\text{C}$
Idss2 @ $T_j=25^\circ\text{C}$	Drain to source leakage current	0	5	50		$V_{cc} = 40\text{V}$, $T_j = 25^\circ\text{C}$
V clamp 1	Drain to source clamp voltage 1	47	52	56	V	$I_d = 20\text{mA}$ (see Fig.3 & 4)
V clamp 2	Drain to source clamp voltage 2	50	53	60		$I_d = I_{shutdown}$ (see Fig.3 & 4)
Vin clamp	IN to source clamp voltage	7	8.1	9.5		$I_{in} = 1\text{ mA}$
Vth	IN threshold voltage	1	1.6	2		$I_d = 50\text{mA}$, $V_{ds} = 14\text{V}$
lin, -on	ON state IN positive current	25	90	200	μA	$V_{in} = 5\text{V}$
lin, -off	OFF state IN positive current	50	130	250		$V_{in} = 5\text{V}$ over-current triggered

Switching Electrical Characteristics

$V_{cc} = 14\text{V}$, Resistive Load = 5Ω , $R_{in} = 50\Omega$, $100\mu\text{s}$ pulse, $T_j = 25^\circ\text{C}$, (unless otherwise specified).

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
Ton	Turn-on delay time	0.05	0.3	0.6	μs	See figure 2
Tr	Rise time	0.4	1	2		
Trf	Time to 130% final Rds(on)	—	8	—		
Toff	Turn-off delay time	0.8	2	3.5		See figure 2
Tf	Fall time	0.5	1.5	2.5		
Qin	Total gate charge	—	11	—	nC	$V_{in} = 5\text{V}$

Protection Characteristics

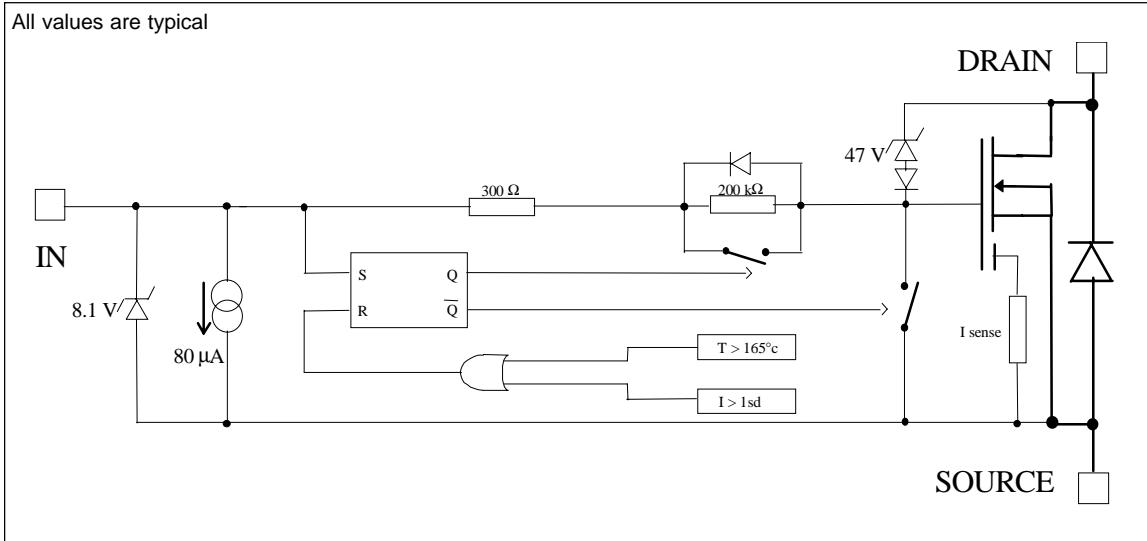
Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
Tsd	Over temperature threshold	—	165	—	$^\circ\text{C}$	See fig. 1
Isd	Over current threshold	10	14	18	A	See fig. 1
Vreset	IN protection reset threshold	1.5	2.3	3	V	
Treset	Time to reset protection	2	10	40	μs	$V_{in} = 0\text{V}$, $T_j = 25^\circ\text{C}$
EOI_OT	Short circuit energy (see application note)	—	400	—	μJ	$V_{cc} = 14\text{V}$

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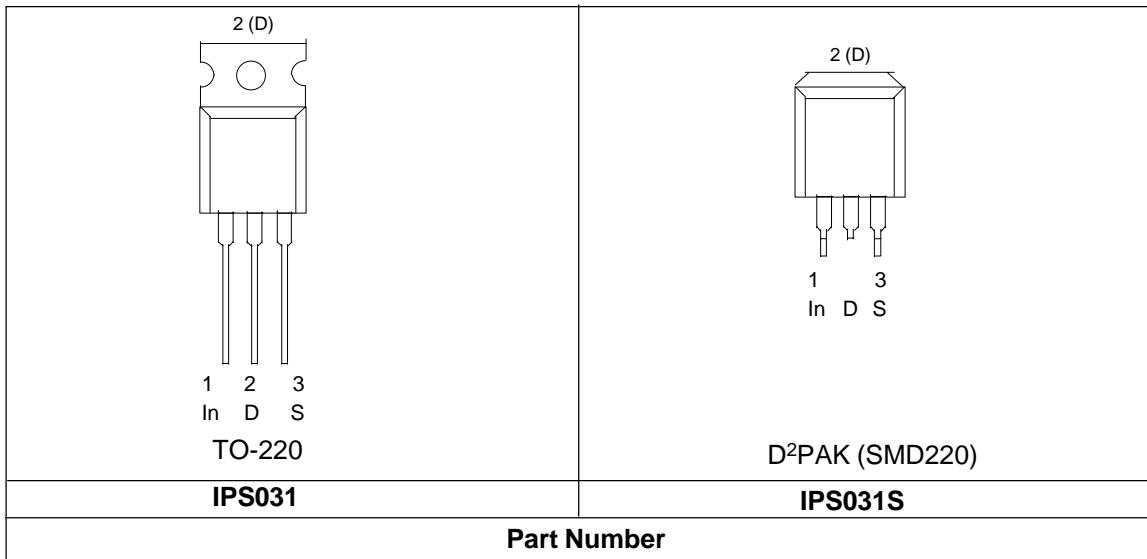
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Functional Block Diagram

All values are typical



Lead Assignments



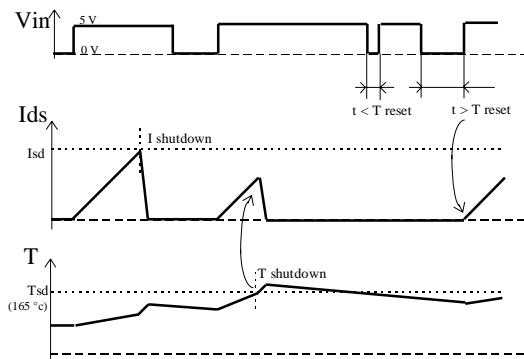


Figure 1 - Timing diagram

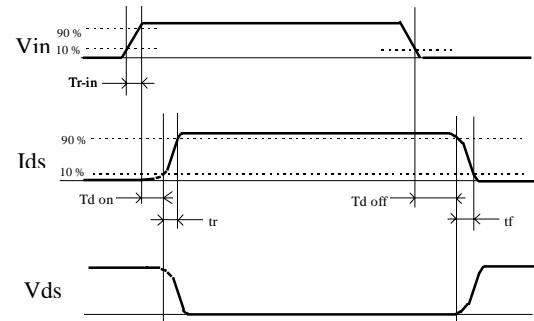


Figure 2 - IN rise time & switching time definitions

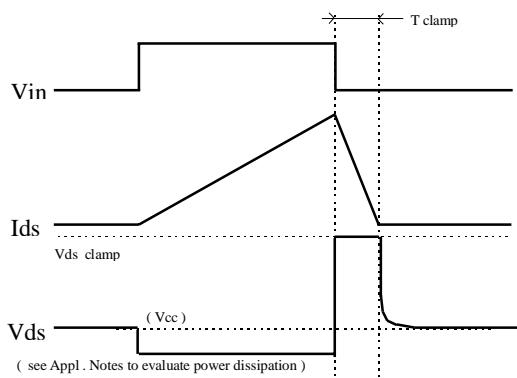


Figure 3 - Active clamp waveforms

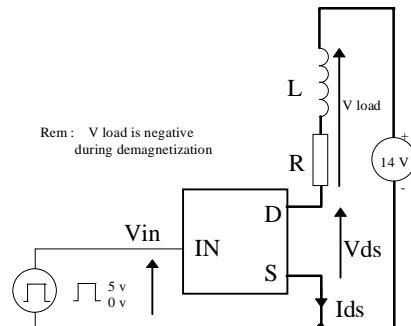


Figure 4 - Active clamp test circuit

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All curves are typical values with standard footprints. Operating in the shaded area is not recommended.

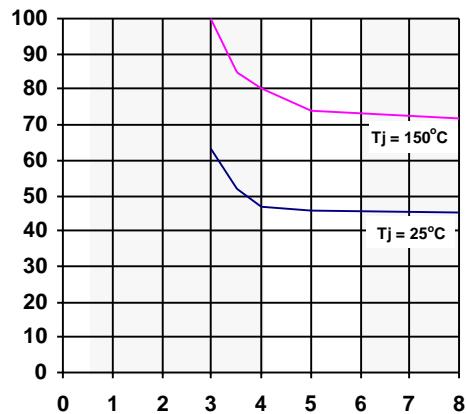


Figure 5 - $R_{DS(on)}$ (mΩ) Vs V_S (V)

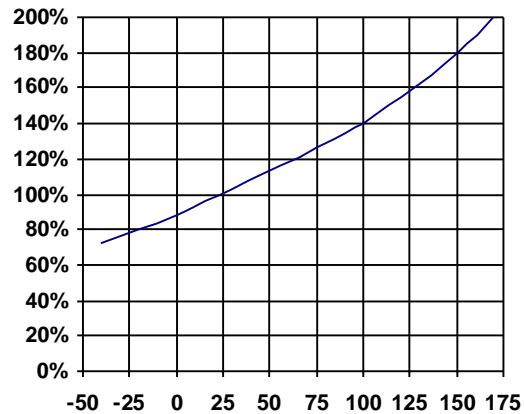


Figure 6 - Normalised $R_{DS(on)}$ (%) Vs T_J ($^\circ\text{C}$)

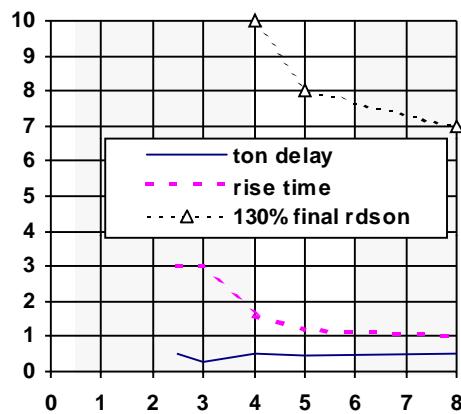


Figure 7 - Turn-ON Delay Time, Rise Time & Time to 130% final $R_{DS(on)}$ (us) Vs V_S (V)

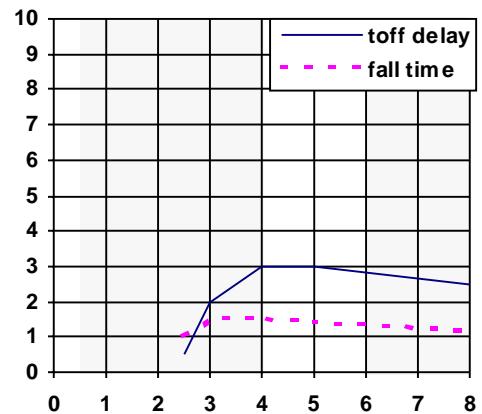


Figure 8 - Turn-OFF Delay Time & Fall Time (us) Vs V_S (V)

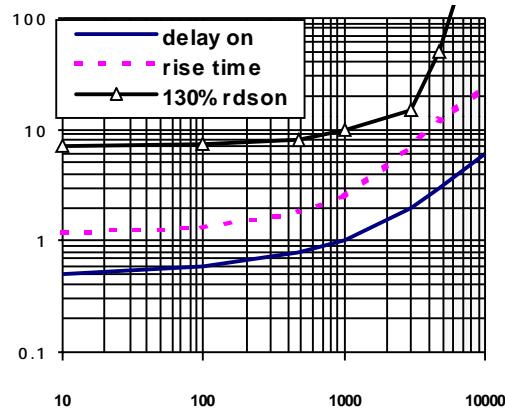


Figure 9 - Turn-ON Delay Time, Rise Time & Time to 130% final $R_{ds(on)}$ (us) Vs IN Resistor (Ω)

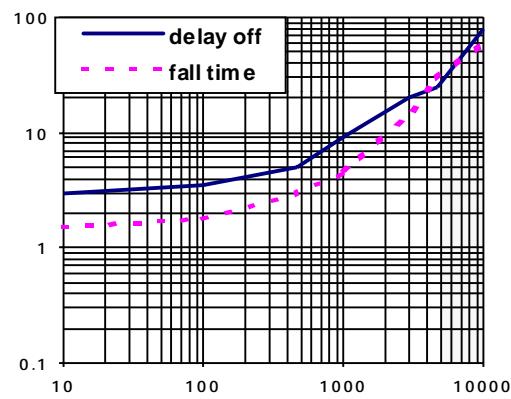


Figure 10 - Turn-OFF Delay Time & Fall Time (us) Vs IN Resistor (Ω)

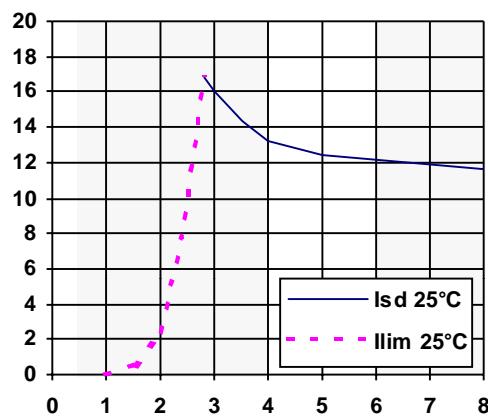


Figure 11 - Current limitation & I shutdown (A) Vs V_{in} (V)

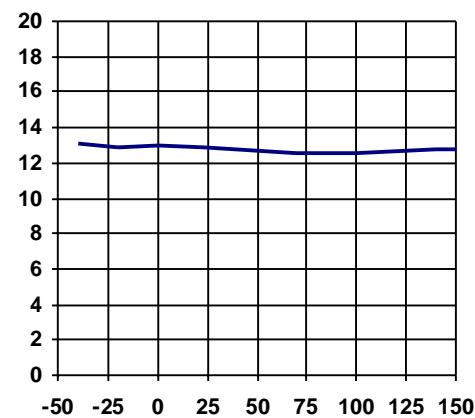


Figure 12 - I shutdown (A) Vs Temperature (°C)

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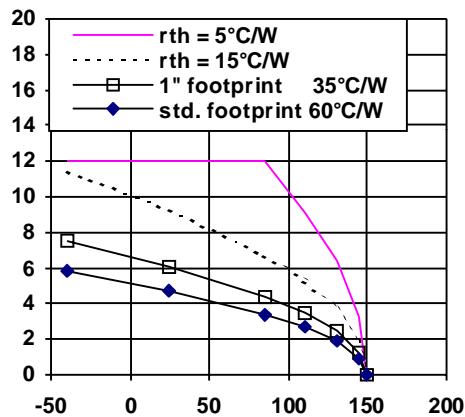


Figure 13 - Max.Cont. Ids (A) Vs Amb.
Temperature (°C)

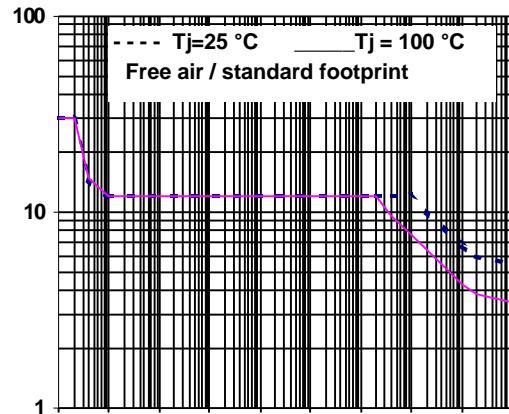


Figure 14 - Ids (A) Vs Protection Resp. Time (s)
IPS031 & IPS031S

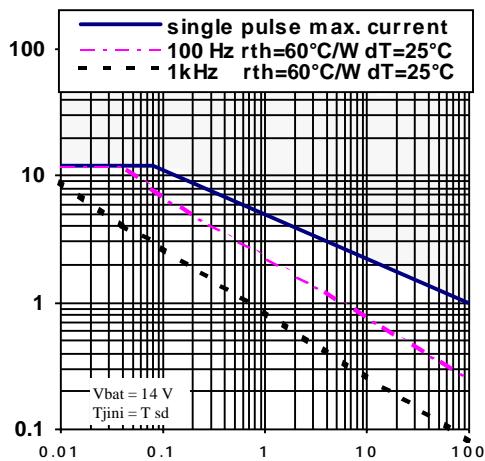


Figure 15 - Iclamp (A) Vs Inductive Load (mH)

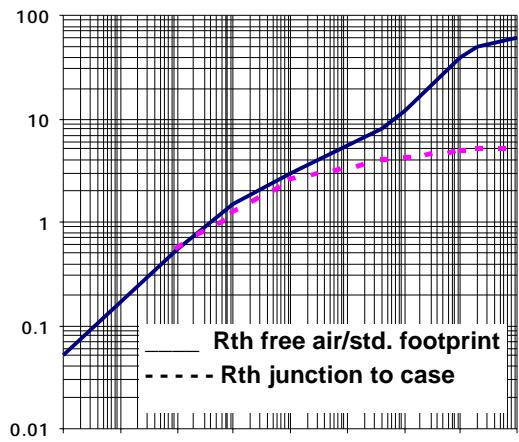


Fig.16 - Transient Thermal Impedance (°C/W)
Vs Time (s) - IPS031/IPS031S

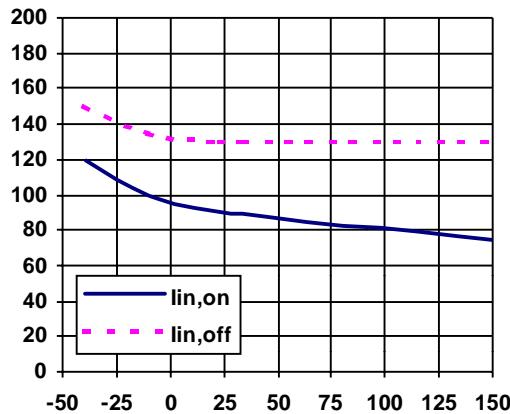


Figure 17 - Input current (μA) Vs Junction ($^{\circ}\text{C}$)

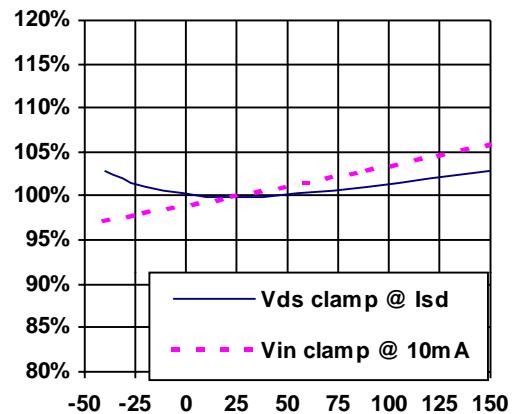


Figure 18 - Vin clamp and V clamp2 (%)
 Vs T_j ($^{\circ}\text{C}$)

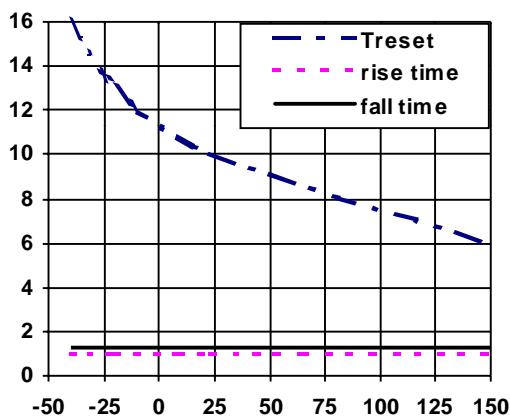
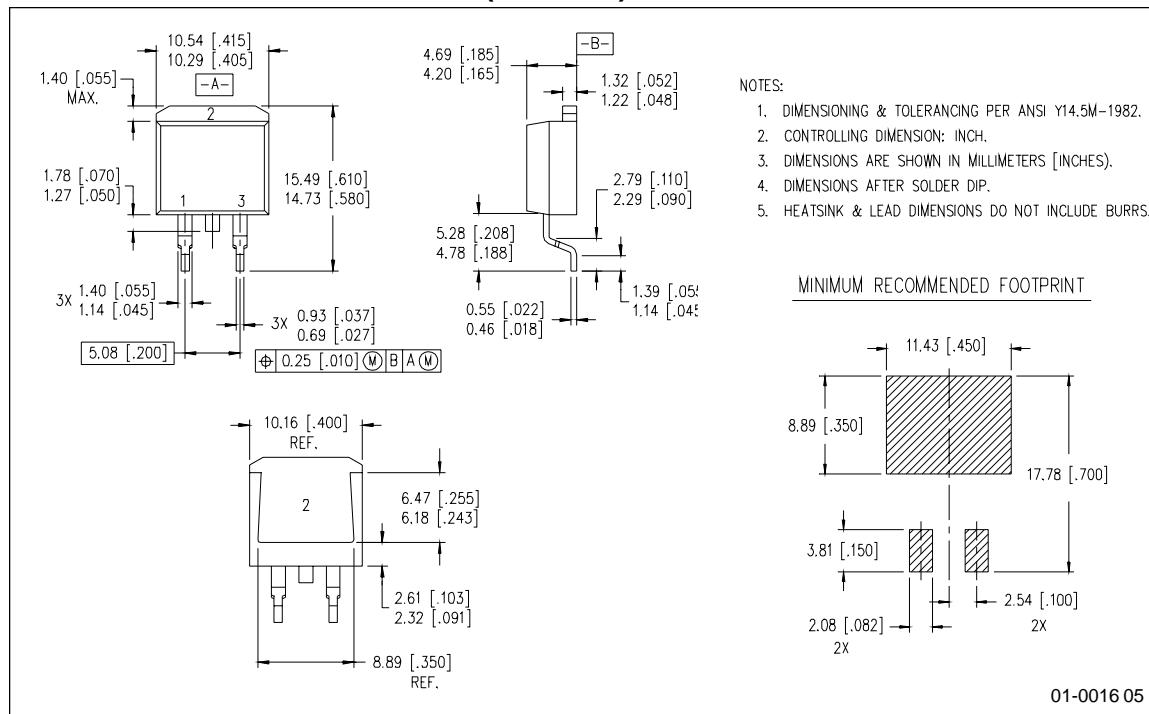
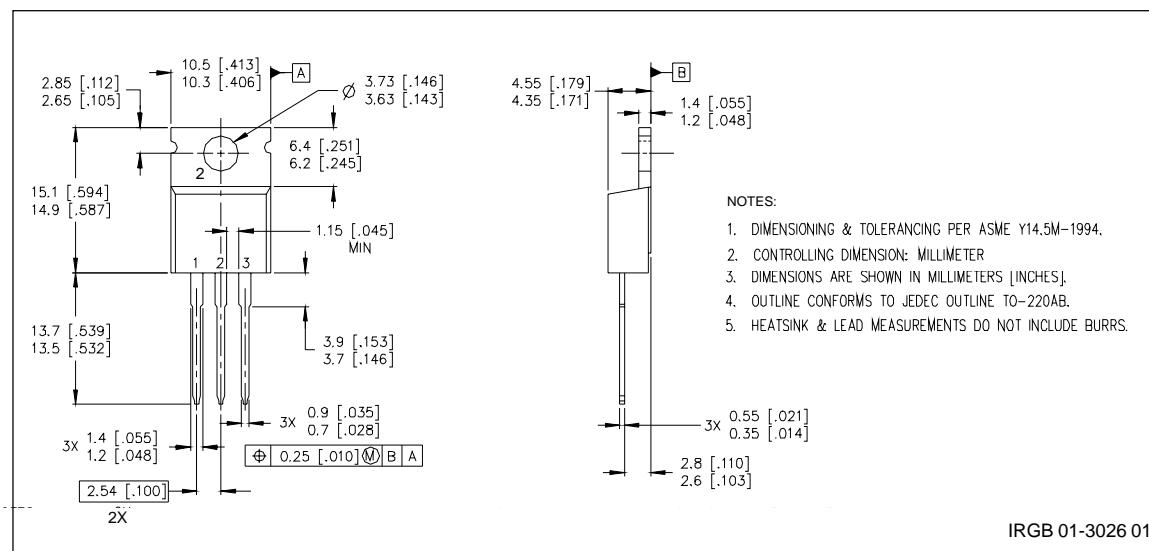


Figure 19 - Turn-on, Turn-off, and treset (μs)
 Vs T_j ($^{\circ}\text{C}$)

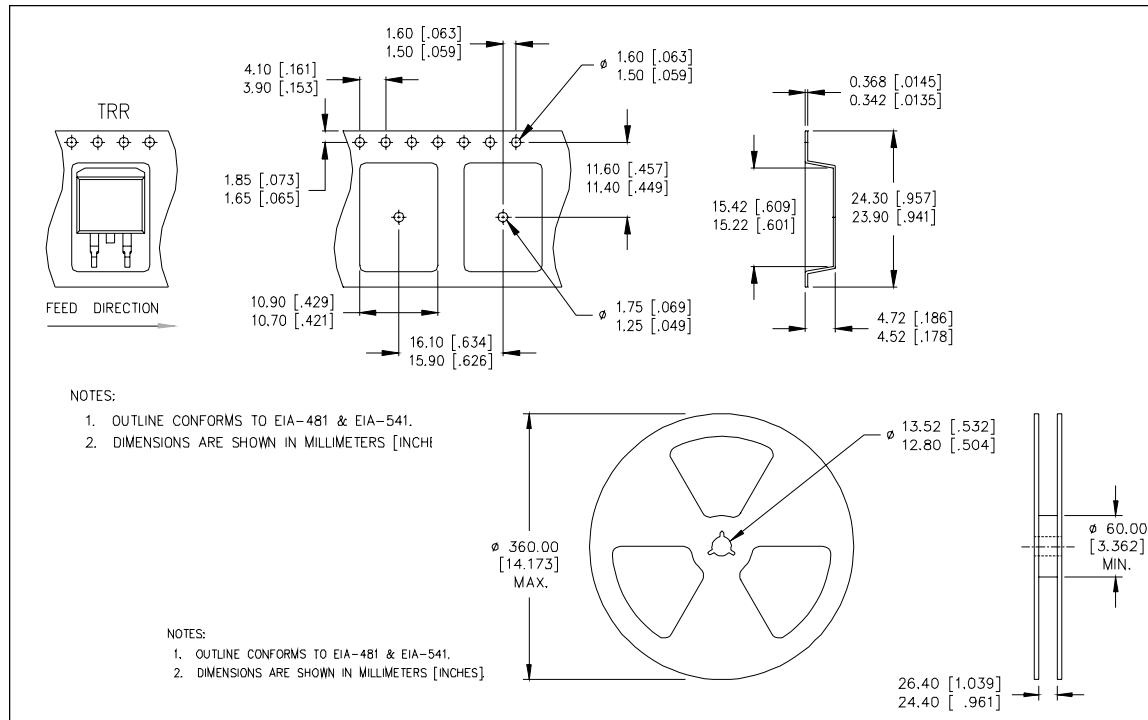
Case Outline 3 Lead - D²PAK (SMD220)



Case Outline 3 Lead - TO220



Tape & Reel - D²PAK (SMD220)



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IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245 Tel: (310) 252-7105

IR EUROPEAN REGIONAL CENTRE: 439/445 Godstone Rd., Whyteleafe, Surrey CR3 0BL, United Kingdom
 Tel: ++ 44 (0) 20 8645 8000

IR JAPAN: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo, Japan 171-0021 Tel: 8133 983 0086

IR HONG KONG: Unit 308, #F, New East Ocean Centre, No. 9 Science Museum Road, Tsimshatsui East, Kowloon
 Hong Kong Tel: (852) 2803-7380

Data and specifications subject to change without notice. 4/16/2000